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ABSTRACT OF THE INVENTION

An improved placing method and placing apparatus are provided for placing
conductive balls in a predetermined pattern onto a base unit. In the placing method for
placing balls having conductivity in a predetermined pattern onto one surface of the
5 base unit, an arrangement member has one surface, another surface opposite to the one
surface of the arrangement member and positioning openings, wherein the positioning
openings are arranged corresponding to the pattern such that the openings are through
from the one surface to the another surfaces of the arrangement member so that the
balls are inserted therein. The another surface of the arrangement member is positioned
10 opposite to the one surface of the base unit. The arrangement member has two or more
line members of which the core axes are substantially aligned. The transfer device is
arranged in a manner that the line members are substantially in a horizontal position to
contact with the balls supplied to one surface of the arrangement member, and then the
transfer device is horizontally moved with respect to the one surface of the arrangement
15 member. Then, the balls are placed on the one surface of the base unit through the
positioning openings.



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